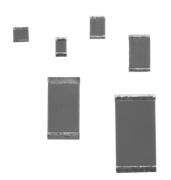


ESCC (4001/026 Qualified R Failure Rate High Precision Thick Film Chip Resistors

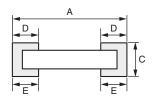


LINKS TO ADDITIONAL RESOURCES



Vishay Sfernice thick film chip resistors CHPFR are specially designed to meet the requirements of the ESCC 4001/026 specification. They have undergone the CNES evaluation (Space French National Agency). They are in level 1 of the ESCC EPPL (European Preferred Part List) and ESCC qualified. At the end of production a 100 % overload screening is performed.

DIMENSIONS in millimeters



FEATURES

HALOGEN FREE

- Load life stability at ± 70 °C for 2000 h: 2.5 % under P_n
- Temperature coefficient to: 100 ppm/°C
- HCHP option R0094: for high frequency applications (up to 10 GHz)
- Tolerances down to 1 %
- R failure rate (level E7)
- SMD wraparound chip resistor
- Generic specification ESCC 4001
- Detailed specification ESCC 4001/026
- · Robust terminations
- Large ohmic value range 1 Ω to 10 M Ω
- ESCC (@) qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Thin film technology terminations, with nickel barrier, are very convenient for high operating conditions. They can withstand thousands of very severe thermal shocks.

- SnPb (W/A) terminations over nickel barrier for solder reflow (variant 11 to 15)
- Gold (W/A) terminations gold over nickel barrier for gluing (variant 16 to 20)



					DI	MENSIONS	in millimete	ers			
VARIANT NUMBER	STYLE	-	4	E	3	()	I)	I	.
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.
11, 16	0603	1.36	1.68	0.72	0.98	0.38	0.53	0.17	0.51	0.25	0.51
12, 17	0805 (1)	1.75	2.07	1.14	1.4	0.38	0.53	0.17	0.51	0.25	0.51
13, 18	1206	2.89	3.21	1.47	1.73	0.38	0.53	0.17	0.51	0.25	0.51
14, 19	2010	4.92	5.24	2.41	2.67	0.5	0.63	0.25	0.64	0.25	0.64
15, 20	2512	6.19	6.51	2.93	3.32	0.5	0.63	0.25	0.64	0.25	0.64

Note

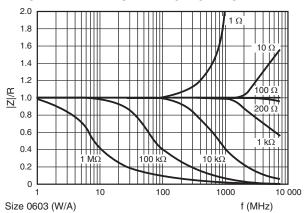
(1) Model CHPFR0805 being same size than case 0705 with same performances, only codification of CHPFR0805 remains



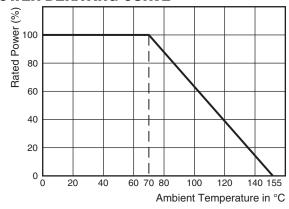
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CLIMATIC SPECIFICATIONS			
Operating temperature range	-55 °C; +155 °C		
Soldering temperature (T _{sol})	Thick film (ruthenium oxyde)		

TYPICAL HF PERFORMANCE OF HCHP



POWER DERATING CURVE



MECHANICAL SPECIFICATIONS			
Substrate Alumina			
Technology	Thick film (ruthenium oxyde)		
Protection	Epoxy coating		
Terminations	B (W/A): SnPb over nickel barrier for solder reflow G (W/A) type: gold over nickel barrier for gluing		

PACKAGING

Waffle-pack or tape and reel when specified

	NUMBER O	F PIECES PEI	R PACKAGE	
SIZE	WAFFLE	TAPE AN	TAPE WIDTH	
	PACK 2" x 2"	MIN.	MAX.	WIDIH
0603	100		5000	
0805	100		4000	8 mm
1206	140	100	4000	
2010	60		2000	12 mm
2512	45		2000	12 mm

Note

(1) MOQ for tape and reel: 50 pieces

SUGGESTED LAND PATTERN (please refer to IPC-7351A)



CHIP SIZE	Z _{max.}	G _{min.}	X _{max} .
0603	2.38	0.34	0.98
0805	2.77	0.73	1.40
1206	3.91	1.87	1.73
2010	5.94	3.64	2.67
2512	7.21	4.91	3.32





STANDA	STANDARD ELECTRICAL SPECIFICATIONS						
MODEL	SIZE	RESISTANCE RANGE R_n	POWER RATING (1) W	TOLERANCE (2) ± %	TEMPERATURE COEFFICIENT (2) (± 10 ⁻⁶ /°C)	CRITICAL RESISTANCE kΩ	TERMINAL MATERIAL AND FINISH
CHPFR	0603	1 to 10M	0.1	1, 2, 5	100, 200	25	E4
CHPFR	0805	1 to 10M	0.2	1, 2, 5	100, 200	50	E4
CHPFR	1206	1 to 10M	0.25	1, 2, 5	100, 200	160	E4
CHPFR	2010	1 to 10M	0.5	1, 2, 5	100, 200	180	E4
CHPFR	2512	1 to 10M	0.8	1, 2, 5	100, 200	112.5	E4
CHPFR	0603	1 to 10M	0.1	1, 2, 5	100, 200	25	E2
CHPFR	0805	1 to 10M	0.2	1, 2, 5	100, 200	50	E2
CHPFR	1206	1 to 10M	0.25	1, 2, 5	100, 200	160	E2
CHPFR	2010	1 to 10M	0.5	1, 2, 5	100, 200	180	E2
CHPFR	2512	1 to 10M	0.8	1, 2, 5	100, 200	112.5	E2

Notes

TABLE 1

RESISTANCE (Ω)	VALUE SERIES	AVAILABLE TOLERANCE (± %)	AVAILABLE TEMPERATURE COEFFICIENT (± 10 ⁻⁶ /°C)
$1 \le R_n < 10$	A	2, 5	200
$10 \le R_{\rm n} < 1M$	Any value in the resistance range to 3 significant figures	1, 2, 5	100, 200
$R_{\rm n} \ge 1 \rm M$	10 0 Signinoant figures	2, 5	200

MAXIMUM RATINGS						
CHARACTERISTICS	VARIANT NUMBER	STYLE	SYMBOLS	LIMITS	UNITS	REMARKS
	11, 16	0603		50		
	12, 17	0805		100		
Limiting element voltage	13, 18	1206	U_{L}	200	V	-
	14, 19	2010		300		
	15, 20	2512		300		
Rated voltage	All	All	U_{R}	$\sqrt{(P_n \times R_n)}$	V	(1)
	11, 16	0603		100		
	12, 17	0805		200		
Isolation voltage	13, 18	1206	U_{l}	300	V	-
	14, 19	2010		300		
	15, 20	2512		300		
Operating temperature range	All	All	T _{op}	-65 to +155	°C	T _{amb}
Storage temperature range	All	All	T _{stg}	-65 to +155	°C	-
Soldering temperature	All	All	T _{sol}	+260	°C	(2)
	11, 16	0603		0.002		
	12, 17	0805		0.004		
Maximum weight	13, 18	1206		0.008	g	-
	14, 19	2010		0.026		
	15, 20	2512		0.042		

Notes

 $^{^{(1)}}$ At $T_{amb} > +70\ ^{\circ}C$ derate linearly to 0 W at $T_{amb} = +155\ ^{\circ}C$

⁽²⁾ Restrictions might apply depending on ohmic value please refer to Table 1

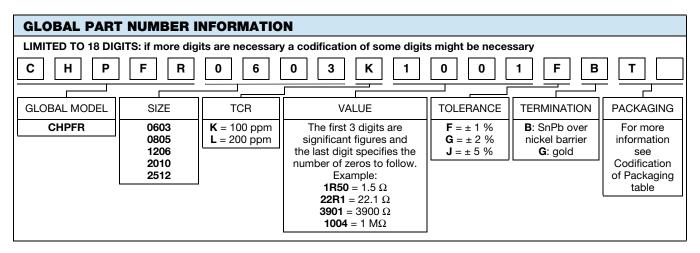
 $^{^{(1)}}$ Shall never exceed limiting element voltage. $R_{\rm n}$ = rated resistance

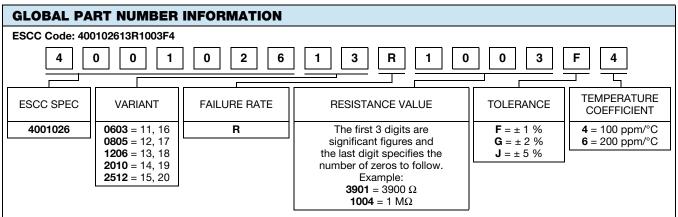
⁽²⁾ Duration 10 s maximum

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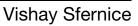
PERFORMANCE					
TEST	CONDITIONS	LIMITS REQUIRED BY THE ESCC4001/026 SPECIFICATION			
Insulation resistance	ESCC4001 § 8.3.1.2 V = 100 V	1000 ΜΩ			
Low temperature electrical measurement	ESCC4001 § 8.3.1.1 TC = 100 ppm/°C TC = 200 ppm/°C	± 0.8 % ± 1.6 %			
High temperature electrical measurement	ESCC4001 § 8.3.3 TC = 100 ppm/°C TC = 200 ppm/°C	± 1.36 % ± 2.72 %			
Rapid change of temperature	ESCC4001 § 8.8	± 0.25 + (0.05 Ω x 100/R _n) %			
Robustness of terminations	ESCC4001 § 8.11.2	$\pm 0.25 + (0.05 \Omega \times 100/R_n) \%$			
Resistance to solder heat	ESCC4001 § 8.12	$\pm 0.5 + (0.05 \Omega \times 100/R_n) \%$			
Climatic sequence	ESCC4001 § 8.10	± 1 + (0.05 Ω x 100/R _n) %			
Load life	ESCC4001 § 8.13 1000 h 2000 h	± 1.5 + (0.05 Ω x 100/R _n) % ± 2.5 + (0.05 Ω x 100/R _n) %			



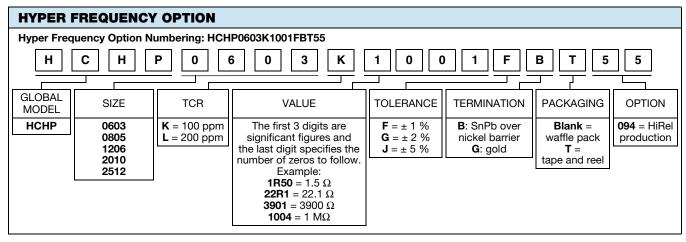


MOQ for tape and reel: 50 pieces

CROSS REFERENCE BETWEEN ESA PART NUMBER AND VISHAY PART NUMBER						
ESA PART NUMBER	VISHAY PART NUMBER EXPLANATIONS					
4001026131003F4	CHPFR1206K1003FB	4001026 = CHPFR	13 = 1206 with B terminations	1003 = 1003 (100 k Ω)	F = F (tol. 1 %)	4 = K (TCR 100 ppm/°C)







CROSS REFERENCE BETWEEN ESA PART NUMBER AND CHPFR PART NUMBER			
VARIANT ESA	VISHAY MODELS		
11	CHPFR0603/B terminations		
12	CHPFR0805/B terminations		
13	CHPFR1206/B terminations		
14	CHPFR2010/B terminations		
15	CHPFR2512/B terminations		
16	CHPFR0603/G terminations		
17	CHPFR0805/G terminations		
18	CHPFR1206/G terminations		
19	CHPFR2010/G terminations		
20	CHPFR2512/G terminations		

CODIF	CODIFICATION OF PACKAGING					
WAFFLE	WAFFLE PACK					
W	100 min., 1 mult.					
WA	100 min., 100 mult. (available only in size 1206)					
PLASTIC	TAPE					
T	100 min., 1 mult.					
TA	100 min., 100 mult.					
TB	250 min., 250 mult.					
TC	500 min., 500 mult.					
TD	1000 min., 1000 mult.					
TE	2500 min., 2500 mult.					
TF	Full tape (quantity depending on size of chips)					
PAPER T	APE					
PT	100 min., 1 mult.					
PA	100 min., 100 mult.					
PB	250 min., 250 mult.					
PC	500 min., 500 mult.					
PD	1000 min., 1000 mult.					
PE	2500 min., 2500 mult.					
PF	Full tape (quantity depending on size of chips)					

CODIFICATION OF OPTIONS ON TWO DIGITS	
OPTION	OPTION 2 DIGITS
0099	99
0100	0A
0101	0B
0102	0C
0103	0D
0104	0E
0105	0F
0124	0Y
0125	0Z
0126	1A
0127	1B
0128	1C
0320	8M
0321	8N
0322	80
0323	8P
0324	8Q
0325	8R

CODIFICATION OF SIZES	
CODE 18	CODE 40
С	0603
D	0805
Н	1206
J	2010
L	2512



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TRACEABILITY DEFINITIONS

The two major traceability elements are defined as:

- The primary process lot number named Front End lot (FE lot). One "FE lot" is composed of several wafers issued from the same thin film deposition sequence.
- The date code named Batch Number (BN). The "BN" is defined after completion of the end of production testing sequence. The lot homogeneity is given by the "FE lot" and not by the "BN".

According to the applied rules validated by the ESCC through the product qualification, the following situations are agreed:

- Parts coming from different "FE lot" might have the same "BN".
- A maximum of two different "BN" might be applied to the same "FE lot" to enable the use of overruns from a previous PO.
- Unless requested / approved by the customer the "BN" will be 2 years old maximum.

SPECIFIC TRACEABILITY REQUIREMENTS

The following specific requirements have to be treated as:

- A customer who requires "Lot Homogeneity" has to mention it on the PO as "SINGLE PRODUCTION LOT".
- A customer who requires "Lot Homogeneity" in addition to a "Single Batch Number" has to mention it on the PO as "SINGLE PRODUCTION LOT AND OPTION R0101".

END OF PRODUCTION TESTING

Mandatory testing performed at the end of the production process:

• 100 % overload: voltage $\sqrt{(6.25 P_n \times R_n)}$ or 2 U_L whichever is less - duration 2 s



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